Title (en)

PRINTED CIRCUIT BOARD AND HEAT SINK ARRANGEMENT

Title (de)

LEITERPLATTEN- UND WÄRMESENKE-ANORDNUNG

Title (fr)

DISPOSITIF DE PLAQUETTE A CIRCUITS IMPRIMES AVEC UN PUITS THERMIQUE

Publication

EP 0807372 A1 19971119 (EN)

Application

EP 96900483 A 19960119

Priority

- CA 9600028 W 19960119
- CA 2141091 A 19950125
- US 51627195 A 19950817

Abstract (en)

[origin: WO9623397A1] Making a heat sink and printed circuit board assembly by providing a heat exchange element on the heat sink which lies in heat exchange contact with the heat sink and passes therethrough. After locating the board and heat sink in relative positions apart and with the heat exchange element aligned with an electronic component on the board, a settable thermally conductive compound is injected through a hole in the heat exchange element to bond it to the electrical component. The heat sink is detachable from the heat exchange element to expose the side of the board carrying the components so that maintenance or repair may be performed. Subsequently the heat sink is returned into its position in the assembly.

IPC 1-7

H05K 7/20; H01L 23/433

IPC 8 full level

H01L 23/40 (2006.01); **H01L 23/433** (2006.01); **H05K 1/02** (2006.01); **H05K 7/20** (2006.01); H05K 3/40 (2006.01)

CPC (source: EP KR)

H01L 23/4006 (2013.01 - EP); **H01L 23/433** (2013.01 - EP); **H05K 1/0206** (2013.01 - EP); **H05K 7/20** (2013.01 - KR); H01L 2023/405 (2013.01 - EP); H01L 2023/4056 (2013.01 - EP); H01L 2023/4062 (2013.01 - EP); H01L 2023/4068 (2013.01 - EP); H01L 2924/0002 (2013.01 - EP); H05K 1/0203 (2013.01 - EP); H05K 3/4069 (2013.01 - EP); H05K 2201/0209 (2013.01 - EP); H05K 2201/066 (2013.01 - EP); H05K 2201/0949 (2013.01 - EP); H05K 2201/0959 (2013.01 - EP); H05K 2201/0969 (2013.01 - EP); H05K 2201/10689 (2013.01 - EP); H05K 2201/10734 (2013.01 - EP); H05K 2203/0126 (2013.01 - EP)

Citation (search report)

See references of WO 9623397A1

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

WO 9623397 A1 19960801; AU 4428396 A 19960814; AU 697409 B2 19981008; CN 1114338 C 20030709; CN 1169235 A 19971231; EP 0807372 A1 19971119; JP 2908881 B2 19990621; JP H10502773 A 19980310; KR 19980701642 A 19980625; MX 9705577 A 19971129

DOCDB simple family (application)

CA 9600028 W 19960119; AU 4428396 A 19960119; CN 96191600 A 19960119; EP 96900483 A 19960119; JP 52251296 A 19960119; KR 19970705036 A 19970724; MX 9705577 A 19960119